

ABSTRACT OF THE DISCLOSURE

In a production process for producing a plurality of semiconductor devices on chip areas which are defined on a wafer, the wafer is processed such that each of the chip areas is produced as a semi-finished semiconductor device by forming a first wiring-arrangement section on each of the chip areas. The wafer is subjected to a provisional yield-rate test in which it is examined whether each of the semi-finished semiconductor devices on the wafer is acceptable or unacceptable to calculate a yield-rate of acceptable semi-finished semiconductor devices. When the wafer passes the provisional yield-rate test, the wafer is further processed such that each of the chip areas is produced as a finished semiconductor device by forming a second wiring-arrangement section on the first wiring-arrangement section.